

In an effort to continually improve products, Samtec has revised LPAM pin geometry. All changes are backwards compatible with existing LPAX. Orders may contain connectors with and without these modifications until inventory is depleted. The void above the solder crimp on the SMT-side of the terminal was removed to improve visual consistency of the solder-joint when inspected by X-ray.

8. Impact of Change on Form, Fit, or Function:

- Form SMT-side terminal geometry will have a small void removed, just above the solder crimp
- Fit Changes are backwards compatible with all existing LPAX; no change to overall size or footprint
- Function The anti-wicking laser-score capability was improved to include all sides of the stamped pin

9. Projected Implementation Date: March 24, 2019

Disclaimer

Please review the change notification details listed above for specific information regarding the nature and timing of the change. While Samtec has taken precautions to ensure this change is not detrimental to your application, each application can be unique and therefore customers should consider the effect of the change on their specific application.

Samtec has taken efforts to ensure that all users of this product who have requested change notifications have been informed. However, you should assume that this is the only notification that will be sent and you, as the recipient, must determine how to communicate this information to your organization(s) and customer(s) as appropriate. If you wish to opt out of receiving Samtec Engineering Change Notification emails, please contact <u>CustomerECN@samtec.com</u>.Due to technical progress, specifications are subject to change without notification and it is recommended to provide an alternative contact when opting out.

Please contact Samtec at <u>CustomerECN@samtec.com</u> for any questions related to this change.